

Attorney Docket No.: 01CON281P

In the Claims:**Claim 1 (currently amended):** A structure comprising:

a laminate substrate having a top surface for receiving a semiconductor die;
an antenna situated on a bottom surface of said laminate substrate, said antenna being suitable for connection to said semiconductor die;
a laminate substrate reference pad in said laminate substrate, said laminate substrate reference pad situated over said antenna;
at least one laminate substrate reference via situated at a side of said antenna, said at least one laminate substrate reference via being electrically connected to said laminate substrate reference pad, said at least one laminate substrate reference via being electrically connected to a printed circuit board reference pad in a printed circuit board.

Claim 2 (original): The structure of claim 1 wherein said laminate substrate reference pad is a laminate substrate ground pad.

Claim 3 (original): The structure of claim 1 wherein said at least one laminate substrate reference via is a laminate substrate ground via.

Claim 4 (canceled).

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Claim 5 (currently amended): The structure of claim 1 wherein said at least one laminate substrate reference via is electrically connected to a printed circuit board reference via in asaid printed circuit board.

Claim 6 (currently amended): The structure of claim 5 wherein said printed circuit board reference via is connected to asaid printed circuit board reference pad.

Claim 7 (original): The structure of claim 1 wherein said laminate substrate comprises an organic material.

Claim 8 (original): The structure of claim 1 wherein said laminate substrate comprises a ceramic material.

Claim 9 (previously presented): The structure of claim 1 wherein a shape of said antenna is selected from the group consisting of a square shape, a rectangular shape, a slot line pattern, a meander line pattern, and a patch pattern.

Claim 10 (original): The structure of claim 1 wherein said at least one laminate substrate reference via is electrically connected to a laminate substrate ball pad on said bottom surface of said laminate substrate.

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Claim 11 (currently amended): A structure comprising:

- a laminate substrate having a top surface for receiving a semiconductor die;
- an antenna situated on a bottom surface of said laminate substrate, said antenna being suitable for connection to said semiconductor die;
- a laminate substrate reference pad in said laminate substrate, said laminate substrate reference pad situated over said antenna;
- a plurality of laminate substrate reference vias, each of said plurality of laminate substrate reference vias situated at a side of said antenna, said each of said plurality of laminate substrate reference vias being electrically connected to said laminate substrate reference pad, said each of said plurality of laminate substrate reference vias being electrically connected to a printed circuit board reference pad in a printed circuit board.

Claim 12 (original): The structure of claim 11 wherein said laminate substrate reference pad is a laminate substrate ground pad.

Claim 13 (original): The structure of claim 11 wherein said each of said plurality of laminate substrate reference vias is a laminate substrate ground via.

Claim 14 (canceled).

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Claim 15 (currently amended): The structure of claim 11 wherein said each of said plurality of laminate substrate reference vias is electrically connected to a respective one of a plurality of printed circuit board reference vias in asaid printed circuit board.

Claim 16 (original): The structure of claim 15 wherein each of said plurality of printed circuit board reference vias is electrically connected to asaid printed circuit board reference pad.

Claim 17 (original): The structure of claim 11 wherein said laminate substrate comprises an organic material.

Claim 18 (original): The structure of claim 11 wherein said laminate substrate comprises a ceramic material.

Claim 19 (previously presented): The structure of claim 11 wherein a shape of said antenna is selected from the group consisting of a square shape, a rectangular shape, a slot line pattern, a meander line pattern, and a patch pattern.

Claim 20 (original): The structure of claim 11 wherein said each of said laminate substrate reference vias is electrically connected to a respective one of a plurality of laminate substrate ball pads on said bottom surface of said laminate substrate.